80-M3126PB100M703-K817F70
datasheet

MiniSKiiP® PACK 3 | **1200 V / 100 A**

Topology features

- Inverter
- Kelvin Emitter for improved switching performance
- Temperature sensor

Component features

- Easy paralleling
- Low turn-off losses
- Low collector emitter saturation voltage
- Positive temperature coefficient
- Short tail current
- Switching optimized for EMC

Housing features

- Base isolation: Al_2O_3
- Easy assembly in one mounting step
- Flexible PCB design w/o pin holes
- Rugged solderless spring contacts

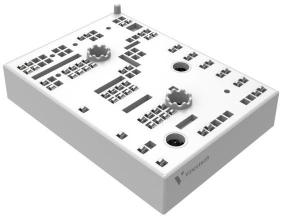
Target applications

- Servo Drives

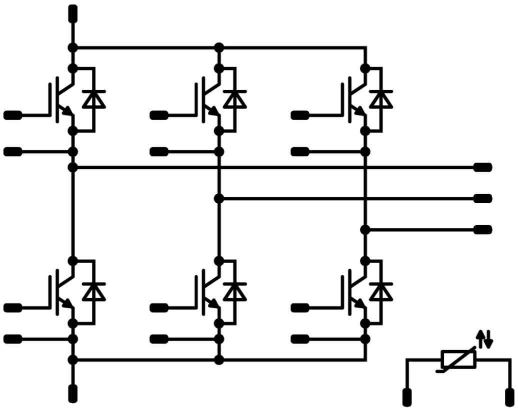
Types

- 80-M3126PB100M703-K817F70

MiniSKiiP® 3 16 mm housing



Schematic



Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions		Value	Unit
Inverter Switch					
Collector-emitter voltage	V_{CES}			1200	V
Collector current (DC current)	I_C	$T_j = T_{jmax}$	T_s = 80 °C	114	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}		200	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	240	W
Gate-emitter voltage	V_{GES}			±20	V
Short circuit ratings	t_{SC}	V_{GE} = 15 V, V_{CC} = 800 V	T_j = 150 °C	9,5	μs
Maximum junction temperature	T_{jmax}			175	°C
Inverter Diode					
Peak repetitive reverse voltage	V_{RRM}			1200	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$	T_s = 80 °C	81	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}		200	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	149	W
Maximum junction temperature	T_{jmax}			175	°C
Module Properties					
Thermal Properties					
Storage temperature	T_{stg}			-40…+125	°C
Operation temperature under switching condition	T_{jop}			-40…+(T_{jmax} - 25)	°C
Isolation Properties					
Isolation voltage	V_{isol}	DC Test Voltage*	t_p = 2 s	5500	V
Creepage distance		With std lid For more informations see handling instructions		6,3	mm
Clearance		With std lid For more informations see handling instructions		6,3	mm
Comparative Tracking Index	CTI			≥ 600	

*100 % tested in production

Characteristic Values

Parameter	Symbol	Conditions	V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	Unit
Inverter Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$			10	0,01	25	5,4	6	6,6	V
Collector-emitter saturation voltage	V_{CEsat}		15		100	25 125 150		1,61 1,82 1,91	1,85(1)	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			100	µA
Gate-emitter leakage current	I_{GES}		20	0		25			200	nA
Internal gate resistance	r_g							None		Ω
Input capacitance	C_{ies}		0	10		25		21000		pF
Output capacitance	C_{oes}		0	10		25		700		pF
Reverse transfer capacitance	C_{res}		0	10		25		280		pF
Gate charge	Q_g	V_{CC} = 600 V	0/15		100	25		700		nC
Thermal										
Thermal resistance junction to sink(2)	$R_{th(j-s)}$	λ_{paste} = 2,5 W/mK (HPTP)						0,4		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 4 Ω R_{goff} = 4 Ω	±15	600	100	25 125 150		177,56 176,41 176,65		ns
Rise time	t_r	R_{gon} = 4 Ω R_{goff} = 4 Ω	±15	600	100	25 125 150		30,89 35,89 36,76		ns
Turn-off delay time	$t_{d(off)}$	R_{gon} = 4 Ω R_{goff} = 4 Ω	±15	600	100	25 125 150		194,99 223,67 229,73		ns
Fall time	t_f	R_{gon} = 4 Ω R_{goff} = 4 Ω	±15	600	100	25 125 150		89,83 117,95 132,29		ns
Turn-on energy (per pulse)	E_{on}	Q_{rFWD}=8,01 µC Q_{rFWD}=12,51 µC Q_{rFWD}=13,78 µC	±15	600	100	25 125 150		7,13 9,19 9,86		mWs
Turn-off energy (per pulse)	E_{off}		±15	600	100	25 125 150		7,66 10,63 11,57		mWs

Characteristic Values

Parameter	Symbol	Conditions	V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	Unit
Inverter Diode										
Static										
Forward voltage	V_F				100	25 125 150		1,82 1,96 1,97	2,1(1)	V
Reverse leakage current	I_R	V_r = 1200 V				25			40	µA
Thermal										
Thermal resistance junction to sink(2)	$R_{th(j-s)}$	λ_{paste} = 2,5 W/mK (HPTP)						0,64		K/W
Dynamic										
Peak recovery current	I_{RM}	di/dt=3160 A/µs di/dt=3016 A/µs di/dt=2912 A/µs	±15	600	100	25 125 150		92,97 93,99 94,81		A
Reverse recovery time	t_{rr}					25 125 150		233,75 371,71 405,11		ns
Recovered charge	Q_r					25 125 150		8,01 12,51 13,78		µC
Reverse recovered energy	E_{rec}					25 125 150		2,72 4,6 5,09		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		1232,29 931,37 832,71		A/µs

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Thermistor										
Static										
Rated resistance	R					25		1		kΩ
Deviation of R100	$\Delta_{R/R}$	R_{100} = 1670 Ω				100	-2		2	%
Maximum Current	I_{max}							3		mA
Power dissipation constant	d					25		0,76		mW/K
A-value	A							$7{,}635 \times 10^{-3}$		1/K
B-value	B							$1{,}73 \times 10^{-5}$		$1/K^2$
Vincotech Thermistor Reference									E	

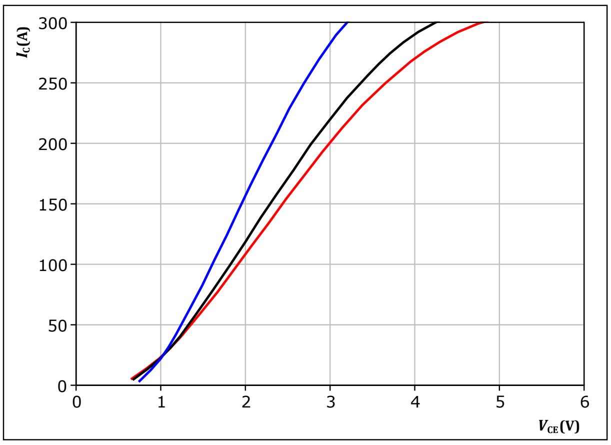
(1) Value at chip level
(2) Only valid with pre-applied Vincotech thermal interface material.

Inverter Switch Characteristics

figure 1. **IGBT**

Typical output characteristics

I_C = f(V_{CE})

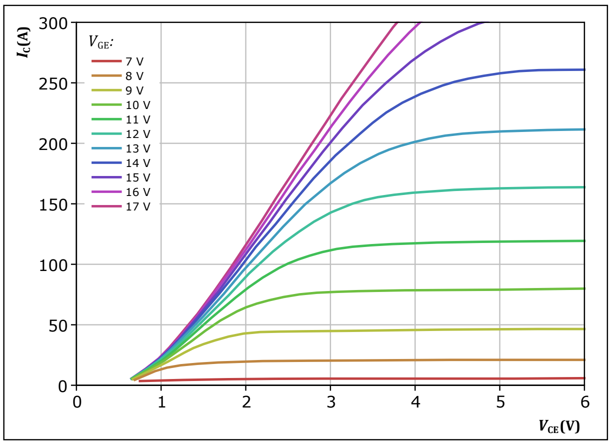


t_p = 250 µs
V_{GE} = 15 V
T_j: 25 °C, 125 °C, 150 °C

figure 2. **IGBT**

Typical output characteristics

I_C = f(V_{CE})

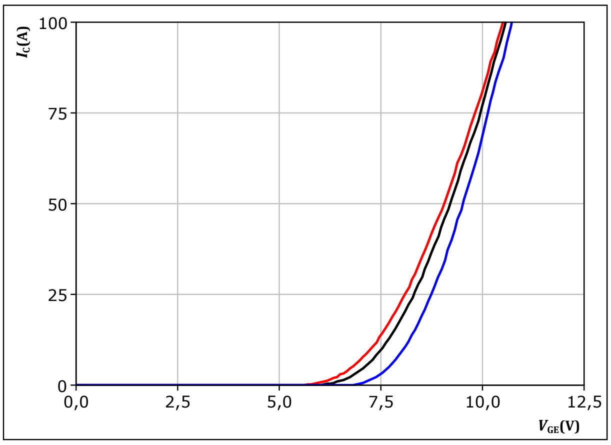


t_p = 250 µs
T_j = 150 °C
V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. **IGBT**

Typical transfer characteristics

I_C = f(V_{GE})

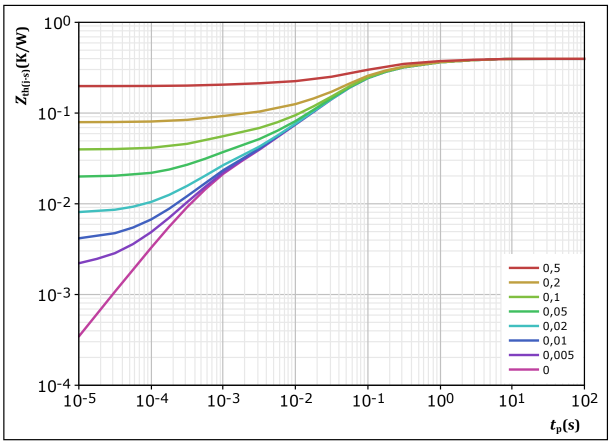


t_p = 250 µs
V_{CE} = 10 V
T_j: 25 °C, 125 °C, 150 °C

figure 4. **IGBT**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)}$ = f(t_p)



D = t_p / T
$R_{th(j-s)}$ = 0,396 K/W

IGBT thermal model values

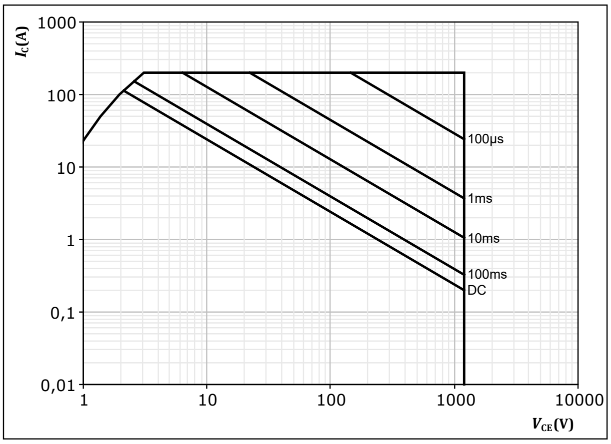
R (K/W)	τ (s)
3,88E-02	2,55E+00
9,12E-02	3,93E-01
2,11E-01	6,52E-02
3,64E-02	9,40E-03
1,85E-02	6,78E-04

Inverter Switch Characteristics

figure 5. **IGBT**

Safe operating area

I_C = f(V_{CE})

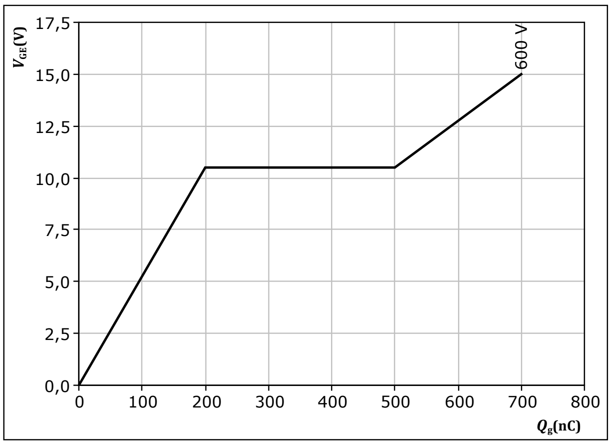


D = single pulse
T_s = 80 °C
V_{GE} = 15 V
T_j = T_{jmax}

figure 6. **IGBT**

Gate voltage vs gate charge

V_{GE} = f(Q_g)



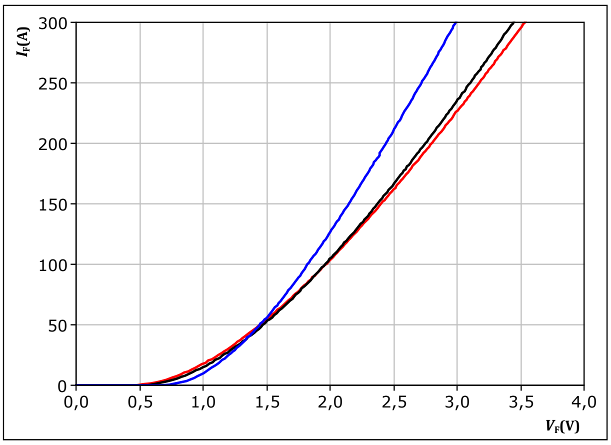
I_C = 100 A
T_j = 25 °C

Inverter Diode Characteristics

figure 7. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



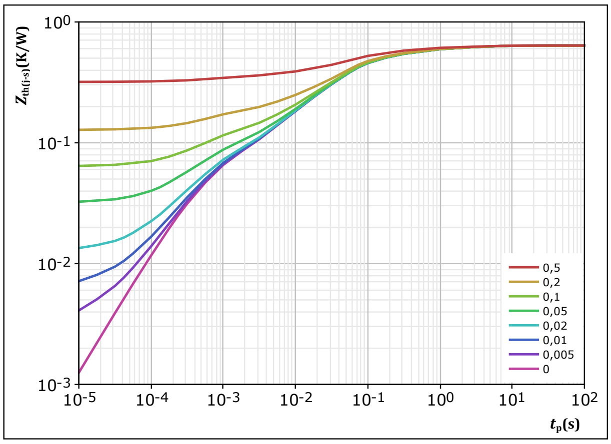
t_p = 250 µs

T_j: 25 °C, 125 °C, 150 °C

figure 8. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



$D = t_p / T$

$R_{th(j-s)}$ = 0,638 K/W

FWD thermal model values

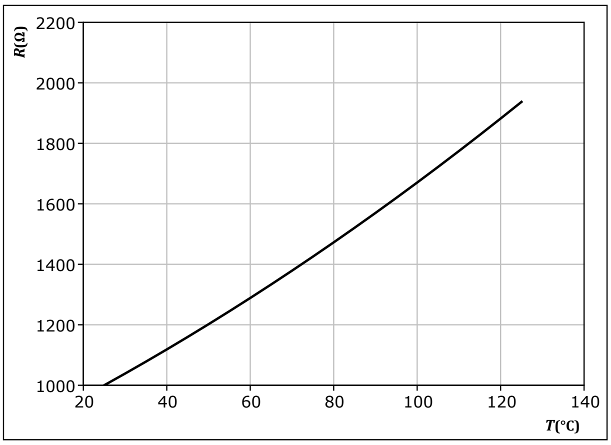
R (K/W)	τ (s)
5,39E-02	2,66E+00
1,18E-01	3,25E-01
3,25E-01	4,92E-02
8,49E-02	7,32E-03
5,61E-02	5,21E-04

Thermistor Characteristics

figure 9. **Thermistor**

Typical PTC characteristic as function of temperature

R_T = f(T)

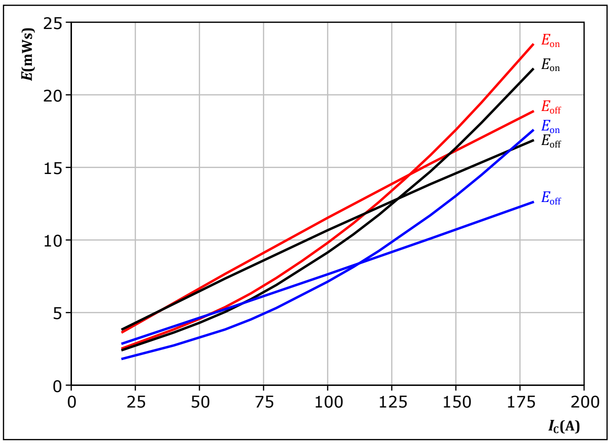


Inverter Switching Characteristics

figure 10. IGBT

Typical switching energy losses as a function of collector current

E = f(I_C)



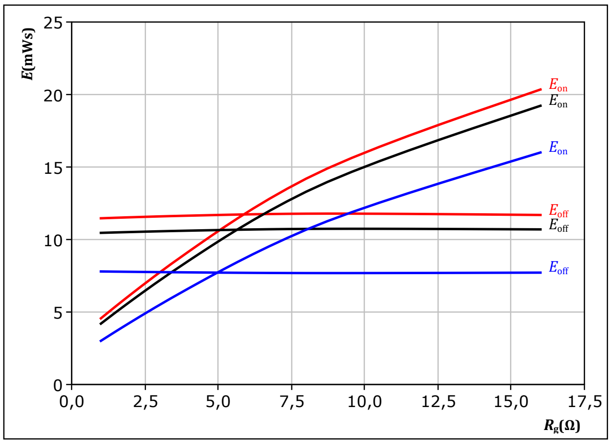
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	4	Ω		150 °C
R_{goff} =	4	Ω		

figure 11. IGBT

Typical switching energy losses as a function of IGBT turn on gate resistor

E = f(R_g)



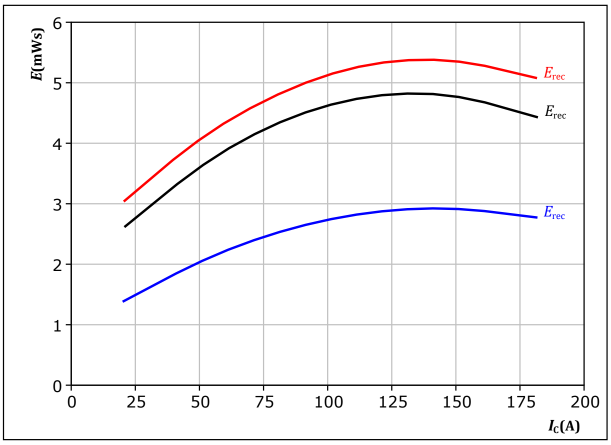
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	100	A		150 °C

figure 12. FWD

Typical reverse recovered energy loss as a function of collector current

E_{rec} = f(I_C)



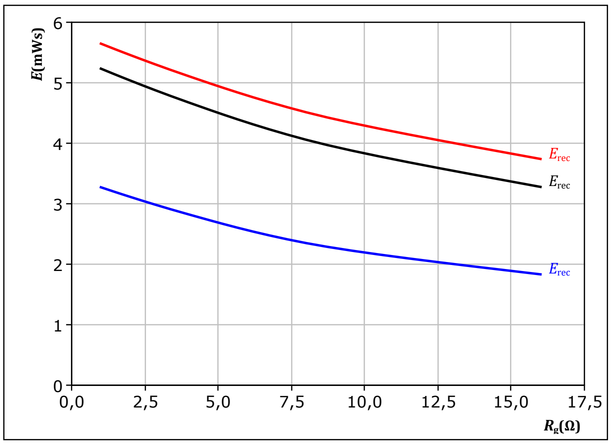
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	4	Ω		150 °C

figure 13. FWD

Typical reverse recovered energy loss as a function of IGBT turn on gate resistor

E_{rec} = f(R_g)



With an inductive load at

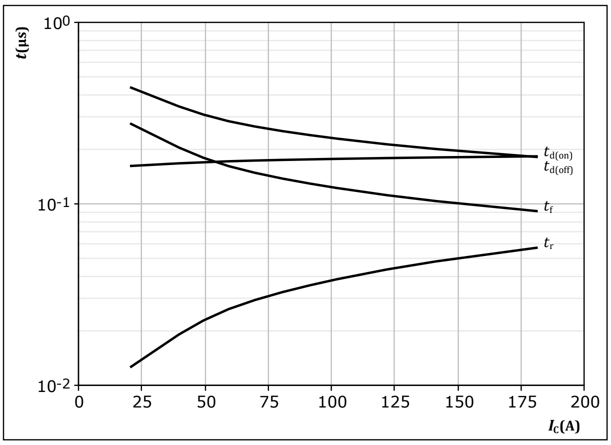
V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	100	A		150 °C

Inverter Switching Characteristics

figure 14. **IGBT**

Typical switching times as a function of collector current

t = f(I_C)



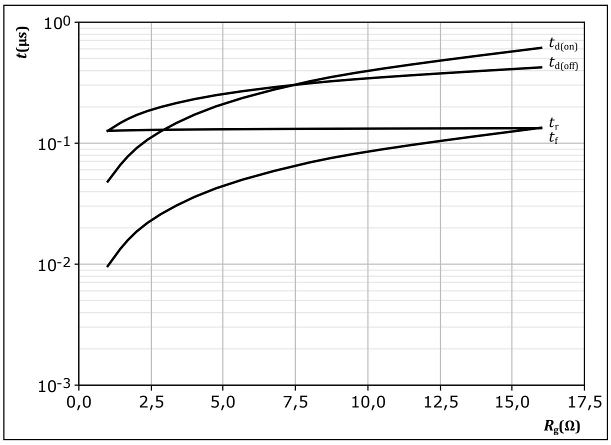
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	4	Ω
R_{goff} =	4	Ω

figure 15. **IGBT**

Typical switching times as a function of IGBT turn on gate resistor

t = f(R_g)



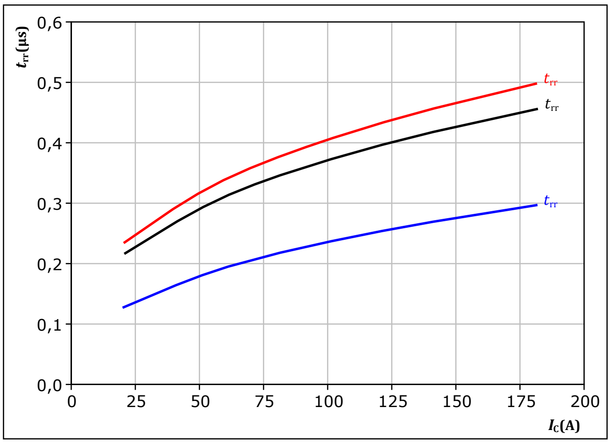
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	100	A

figure 16. **FWD**

Typical reverse recovery time as a function of collector current

t_{rr} = f(I_C)



With an inductive load at

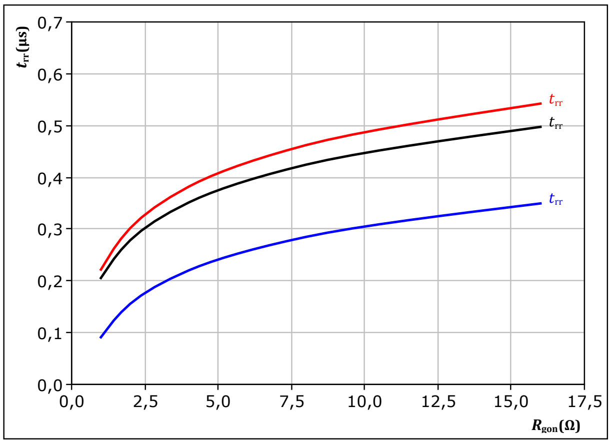
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	4	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 17. **FWD**

Typical reverse recovery time as a function of IGBT turn on gate resistor

t_{rr} = f(R_{gon})



With an inductive load at

V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	100	A

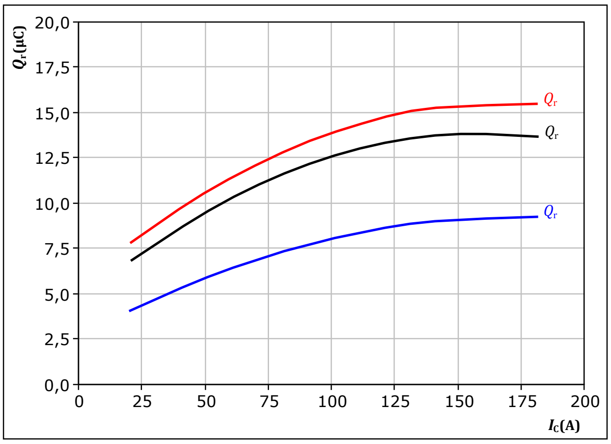
T_j: 25 °C, 125 °C, 150 °C

Inverter Switching Characteristics

figure 18. **FWD**

Typical recovered charge as a function of collector current

Q_r = f(I_C)



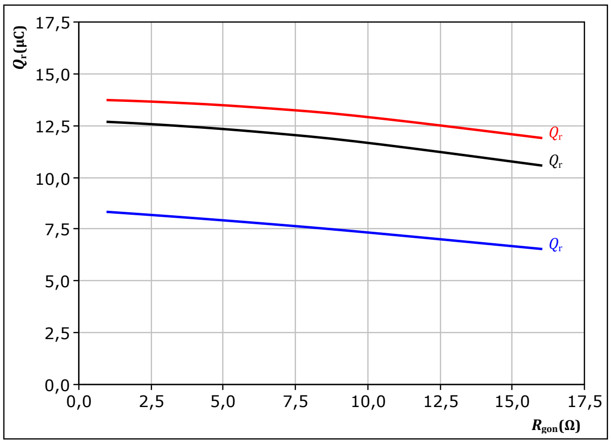
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	4	Ω		150 °C

figure 19. **FWD**

Typical recovered charge as a function of IGBT turn on gate resistor

Q_r = f(R_{gon})



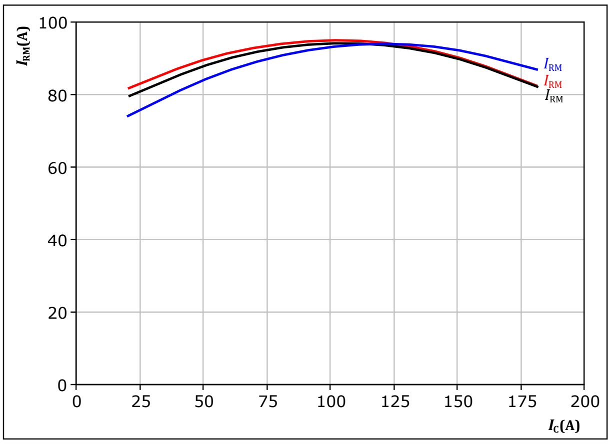
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	100	A		150 °C

figure 20. **FWD**

Typical peak reverse recovery current as a function of collector current

I_{RM} = f(I_C)



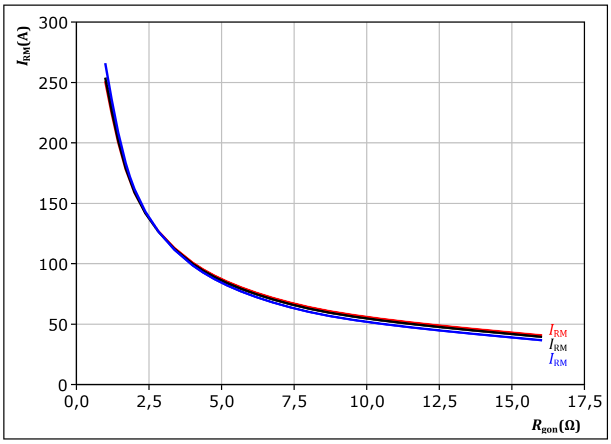
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	4	Ω		150 °C

figure 21. **FWD**

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

I_{RM} = f(R_{gon})



With an inductive load at

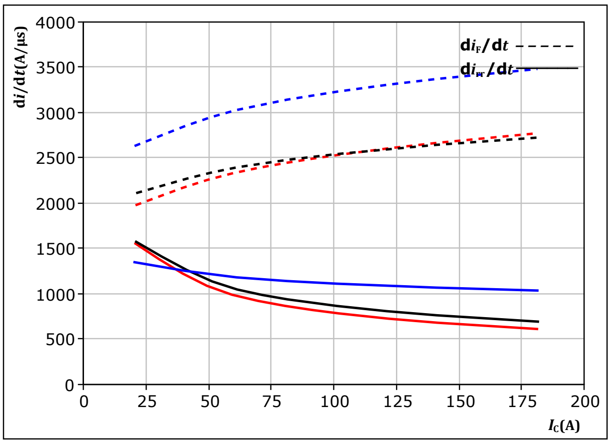
V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	100	A		150 °C

Inverter Switching Characteristics

figure 22. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

di_F/dt, di_{rr}/dt = f(I_C)



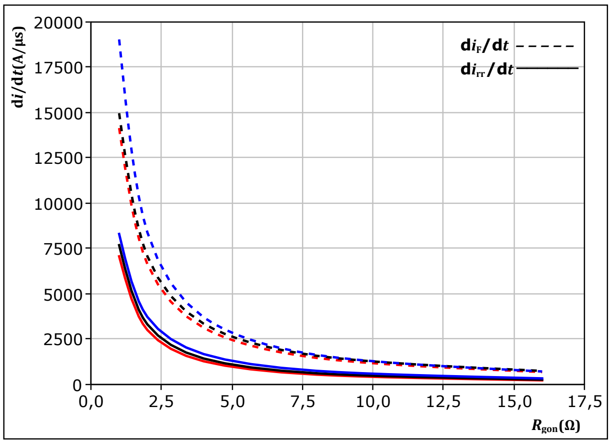
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	4	Ω		150 °C

figure 23. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor

di_F/dt, di_{rr}/dt = f(R_{gon})



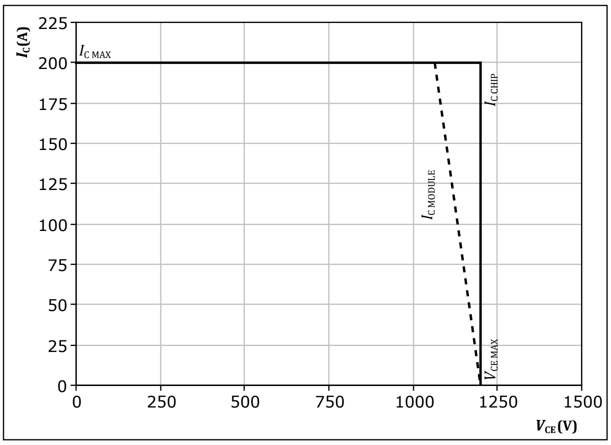
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	100	A		150 °C

figure 24. **IGBT**

Reverse bias safe operating area

I_C = f(V_{CE})



At	T_j =	150	°C
	R_{gon} =	4	Ω
	R_{goff} =	4	Ω

Inverter Switching Definitions

figure 25.	IGBT

Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{tEoff} = integrating time for E_{off})

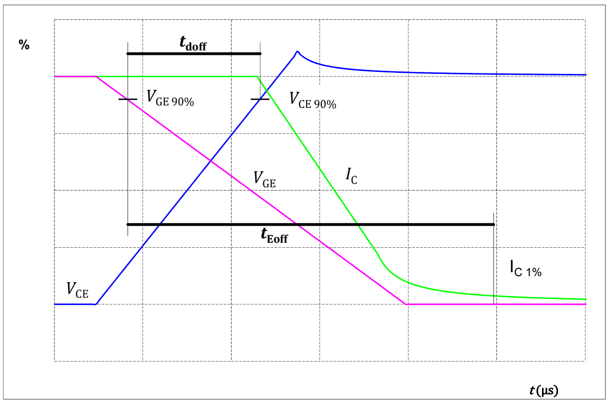


figure 26.	IGBT

Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} = integrating time for E_{on})

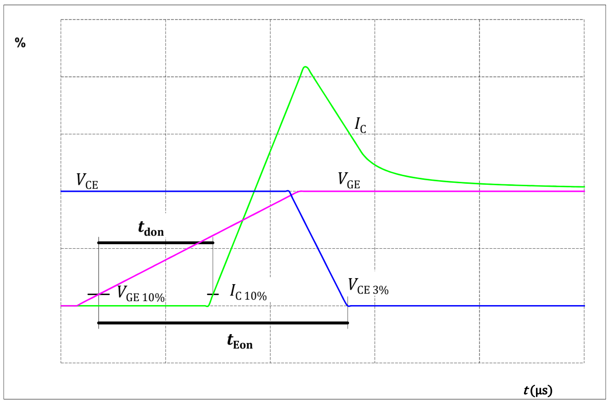


figure 27.	IGBT

Turn-off Switching Waveforms & definition of t_f

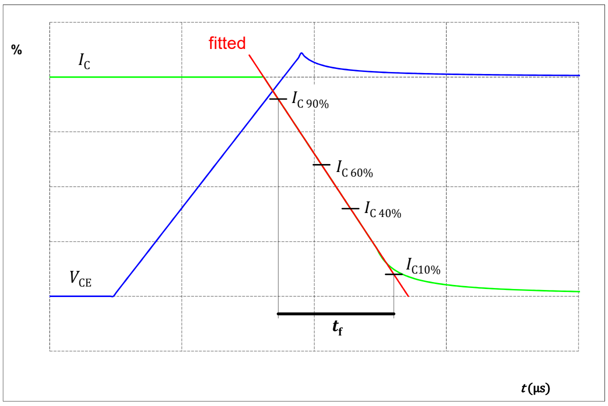
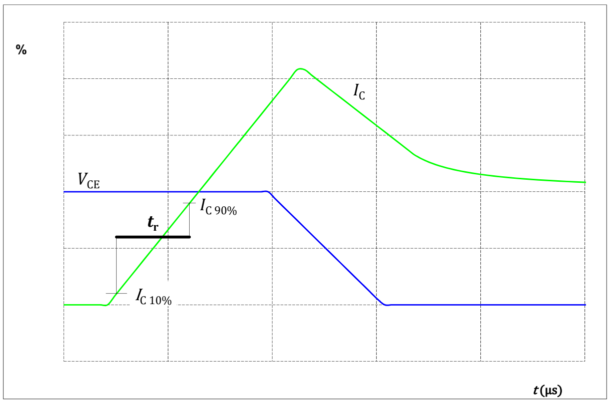


figure 28.	IGBT

Turn-on Switching Waveforms & definition of t_r



Inverter Switching Definitions

figure 29. **FWD**

Turn-off Switching Waveforms & definition of t_{rr}

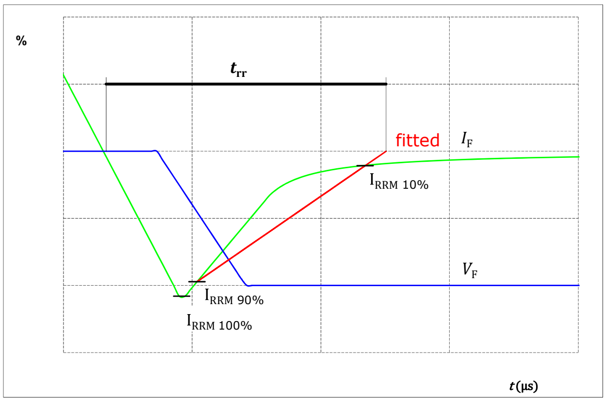
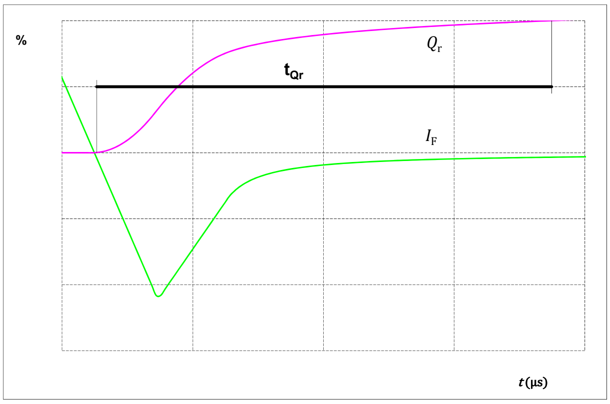


figure 30. **FWD**

Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)



Ordering Code

Version	Ordering Code
With std lid (6.5mm height) + no thermal grease	80-M3126PB100M703-K817F70-/0A/
With thin lid (2.8mm height) + no thermal grease	80-M3126PB100M703-K817F70-/0B/
With std lid (6.5mm height) + thermal grease (0,8 W/mK, P12, silicone-based)	80-M3126PB100M703-K817F70-/1A/
With thin lid (2.8mm height) + thermal grease (0,8 W/mK, P12, silicone-based)	80-M3126PB100M703-K817F70-/1B/
With std lid (6.5mm height) + thermal grease (2,5 W/mK, TG20032, silicone-free)	80-M3126PB100M703-K817F70-/4A/
With thin lid (2.8mm height) + thermal grease (2,5 W/mK, TG20032, silicone-free)	80-M3126PB100M703-K817F70-/4B/
With std lid (6.5mm height) + thermal grease (2,5 W/mK, HPTP, silicone-based)	80-M3126PB100M703-K817F70-/5A/
With thin lid (2.8mm height) + thermal grease (2,5 W/mK, HPTP, silicone-based)	80-M3126PB100M703-K817F70-/5B/

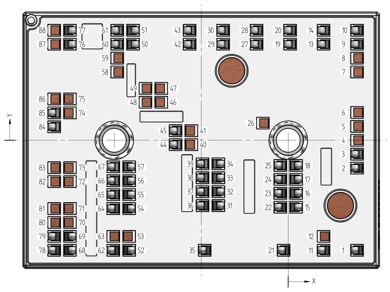
Marking

Text	Name		Date code	UL & VIN	Lot	Serial
	NN-NNNNNNNNNNNNNN-TTTTTTVV		WWYY	UL VIN	LLLLL	SSSS
Datamatrix	Type&Ver	Lot number	Serial	Date code		
	TTTTTTTVV	LLLLL	SSSS	WWYY		

Outline

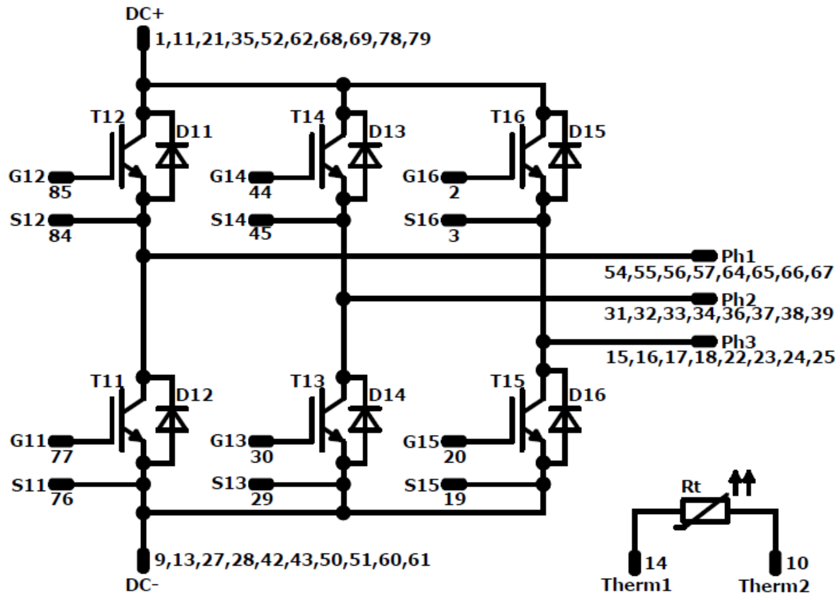
Pin table [mm]

Pin	X	Y	Function	45	-25,9	2,2	S14
1	15,83	-25,3	DC+	46	not assembled		
2	15,83	-6,4	G16	47	not assembled		
3	15,83	-3,2	S16	48	not assembled		
4	not assembled			49	not assembled		
5	not assembled			50	-35,68	22,1	DC-
6	not assembled			51	-35,68	25,3	DC-
7	not assembled			52	-36,58	-25,3	DC+
8	not assembled			53	not assembled		
9	15,83	22,1	DC-	54	-36,58	-15,7	Ph1
10	15,83	25,3	Therm2	55	-36,58	-12,5	Ph1
11	8,13	-25,3	DC+	56	-36,58	-9,3	Ph1
12	not assembled			57	-36,58	-6,1	Ph1
13	8,13	22,1	DC-	58	not assembled		
14	8,13	25,3	Therm1	59	not assembled		
15	1,82	-15,38	Ph3	60	-39,32	22,1	DC-
16	1,82	-12,18	Ph3	61	-39,32	25,3	DC-
17	1,82	-8,98	Ph3	62	-40,22	-25,3	DC+
18	1,82	-5,79	Ph3	63	not assembled		
19	0,43	22,1	S15	64	-40,22	-15,7	Ph1
20	0,43	25,3	G15	65	-40,22	-12,5	Ph1
21	-1,07	-25,3	DC+	66	-40,22	-9,3	Ph1
22	-1,82	-15,38	Ph3	67	-40,22	-6,09	Ph1
23	-1,82	-12,18	Ph3	68	-50,18	-25,3	DC+
24	-1,82	-8,98	Ph3	69	-50,18	-22,1	DC+
25	-1,82	-5,79	Ph3	70	not assembled		
26	not assembled			71	not assembled		
27	-7,27	22,1	DC-	72	not assembled		
28	-7,27	25,3	DC-	73	not assembled		
29	-14,97	22,1	S13	74	not assembled		
30	-14,97	25,3	G13	75	not assembled		
31	-16,05	-15,02	Ph2	76	-50,18	22,1	S11
32	-16,05	-11,82	Ph2	77	-50,18	25,3	G11
33	-16,05	-8,63	Ph2	78	-53,82	-25,3	DC+
34	-16,05	-5,42	Ph2	79	-53,82	-22,1	DC+
35	-19,22	-25,3	DC+	80	not assembled		
36	-19,7	-15,02	Ph2	81	not assembled		
37	-19,7	-11,82	Ph2	82	not assembled		
38	-19,7	-8,62	Ph2	83	not assembled		
39	-19,7	-5,42	Ph2	84	-53,82	3,1	S12
40	not assembled			85	-53,82	6,3	G12
41	not assembled			86	not assembled		
42	-22,67	22,1	DC-	87	not assembled		
43	-22,67	25,3	DC-	88	not assembled		
44	-25,9	-1	G14				



Pad positions refers to center point. For more informations on pad design please see package data

Pinout



Identification

ID	Component	Voltage	Current	Function	Comment
T11, T12, T13, T14, T15, T16	IGBT	1200 V	100 A	Inverter Switch	
D11, D12, D13, D14, D15, D16	FWD	1200 V	100 A	Inverter Diode	
Rt	Thermistor			Thermistor	

Packaging instruction				
Standard packaging quantity (SPQ) 48	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for MiniSKiiP® 3 packages see vincotech.com website.

Package data
Package data for MiniSKiiP® 3 packages see vincotech.com website.

Vincotech thermistor reference
See Vincotech thermistor reference table at vincotech.com website.

UL recognition and file number
This device is UL 1557 recognized under E192116 up to a junction temperature under switching condition $T_{j,op}$=150°C and up to 2500VAC/1min isolation voltage. For more information see vincotech.com website.

Document No.:	Date:	Modification:	Pages
80-M3126PB100M703-K817F70-D1-14	9 Dec. 2025		